

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A semiconductor device comprising:
 - a semiconductor substrate having a pattern forming region and a pattern non-forming region;
 - a wiring pattern formed on said pattern forming region;
 - a plurality of dummy patterns formed on said pattern non-forming region, said plurality of dummy patterns being formed within a plurality of dummy areas each having a same shape; and
 - an insulating film formed on said wiring pattern and said plurality of dummy patterns;

wherein said insulating film is formed by a chemical vapor deposition and is smoothed by chemical mechanical polishing; and

wherein each of said plurality of dummy patterns has a plurality of line patterns each of which is spaced apart with a width filled by plus sizing the deposition of said insulating film formed on said plurality of dummy patterns.

2-4. (Cancelled)

5. (Previously presented) A semiconductor device according to claim 1, wherein the dummy areas each have a square shape.
6. (Previously presented) A semiconductor device according to claim 1, wherein the dummy areas are arranged in lattice form.
7. (Previously presented) A semiconductor device according to claim 1, wherein the width is approximately less than 72 μm .
8. (Previously Presented) A semiconductor device according to claim 1, wherein said plurality of dummy patterns are line patterns.

9. (Currently Amended) A semiconductor device comprising:
a semiconductor substrate having a pattern area and a non-pattern area;
a conductive pattern formed on said pattern area of said semiconductor substrate;
and
a plurality of dummy patterns formed on said non-pattern area of said semiconductor substrate, each of said plurality of dummy patterns having a same rectangular outline as each other and being arranged in a matrix with predetermined spacing; and
an insulating film formed on said writing pattern and said plurality of dummy patterns;
wherein said insulating film is formed by a chemical vapor deposition and is smoothed by chemical mechanical polishing; and
wherein each of said plurality of dummy patterns has an opening so that a pattern ratio of said semiconductor device is reduced.

10. (Previously Presented) A semiconductor device according to claim 9, wherein each of said plurality of dummy patterns has a square outline.

11. (Previously Presented) A semiconductor device according to claim 9, wherein the opening has a square outline.

12. (Previously Presented) A semiconductor device according to claim 9, wherein the opening has a shape of a letter.

13. (Previously Presented) A semiconductor device according to claim 9, wherein the opening has a shape of a plurality of letters.

14. (Currently Amended) A semiconductor device comprising:
a semiconductor substrate having a pattern area and a non-pattern area;
a conductor pattern formed on said pattern area of said semiconductor substrate;

a plurality of dummy patterns formed on said non-pattern area of said semiconductor substrate;

an insulating film formed on said conductive pattern and said plurality of dummy patterns;

wherein said insulating film is formed by a chemical vapor deposition and is smoothed by chemical mechanical polishing;

wherein each of said plurality of dummy patterns are formed in a plurality of dummy areas each having a same shape and being arranged in a matrix with predetermined spacing; and

wherein each of said plurality of dummy patterns has a space portion within each of the dummy areas so that a pattern ratio of said semiconductor device is reduced.

15. (Previously Presented) A semiconductor device according to claim 14, wherein each of said plurality of dummy patterns has a rectangular outline and an opening at the space portion.

16. (Previously Presented) A semiconductor device according to claim 15, wherein the opening has a square outline.

17. (Previously Presented) A semiconductor device according to claim 15, wherein the opening has a shape of a letter.

18. (Previously Presented) A semiconductor device according to claim 15, wherein the opening has a shape of a plurality of letters.

19. (Previously Presented) A semiconductor device according to claim 14, wherein said plurality of dummy patterns are line patterns, and each of the dummy areas has line patterns spaced apart from each other.

20. (Previously Presented) A semiconductor device according to claim 19, wherein the line patterns are arranged with a space therebetween being approximately less than 72 μm .

21. (New) A semiconductor device according to claim 1, wherein the line patterns are arranged in a same direction.